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TI Processing of copper alloys for high strength, electric conductivity, and
bendability
IN Hirano, Yasuo
PA Nippon Mining Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 6 pp.
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AB Cu-(0.4-4.0) Ni-(0.1-1.0)% Si alloys are
soln. treated at $\geq 700^\circ$ for grain size 1-10 μm ,
cold rolled at draft $< 40\%$, and aged at $300-700^\circ$ to increase
strength, elec. cond, and bendability. The alloys optionally contain
0.001-2.0% of Fe, Mg, Al, Cr, Mn, Co, Zn, Ti, Zr, Pb, Cd, In, Ag, and/or
P, and are used for elec. applications. Thus, a Cu-1.6
Ni-0.4% Si alloy processed according to the invention
showed tensile strength 55 kg/mm², elongation 15%, and elec. conductivity 50%

of

Cu standard